

MECHANICAL CASE OUTLINE

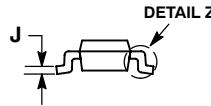
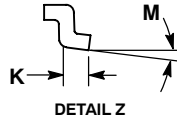
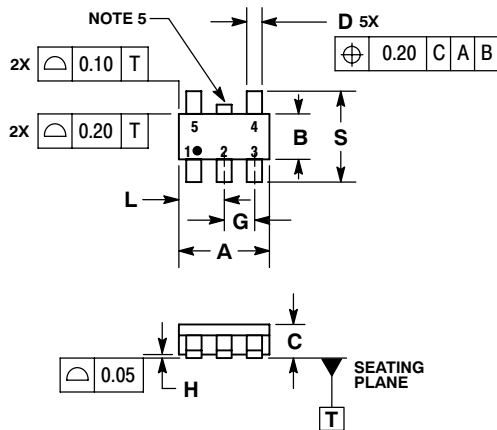
PACKAGE DIMENSIONS

ON Semiconductor®



TSOP-5 CASE 483-02 ISSUE H

DATE 18 MAY 2007

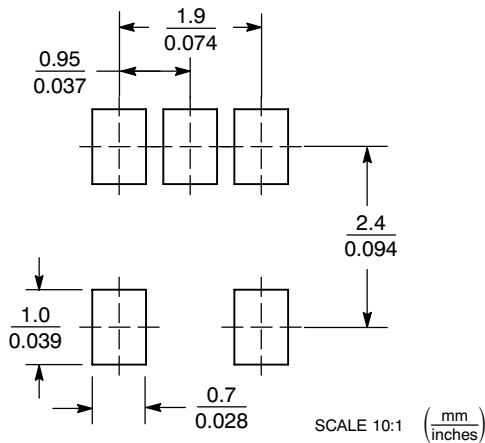


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

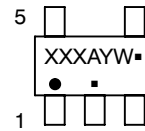
DIM	MILLIMETERS	
	MIN	MAX
A	3.00 BSC	
B	1.50 BSC	
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
L	1.25	1.55
M	0°	10°
S	2.50	3.00

SOLDERING FOOTPRINT*

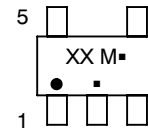


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



Analog



Discrete/Logic

- | | |
|----------------------------|---------------------------|
| XXX = Specific Device Code | XX = Specific Device Code |
| A = Assembly Location | M = Date Code |
| Y = Year | ▪ = Pb-Free Package |
| W = Work Week | |
| ▪ = Pb-Free Package | |

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TSOP-5	PAGE 1 OF 2



ISSUE	REVISION	DATE
O	INITIATED NEW MECHANICAL OUTLINE #483. REQ BY WL CHIN/L. RENNICK.	28 OCT 1998
A	UPDATE OUTLINE DRAWING TO CORRECT DIN "C" (SHOULD BE FROM TIP OF LID TO TOP OF PKG). DIM IN TABLE INCORRECTLY LISTED TO G, F TO H, H TO J, N TO L & R TO M. REQ BY F. PADILLA	13 NOV 1998
B	CHANGE OF LEGAL ONWERSHIP FROM MOTOROLA TO ON SEMICONDUCTOR. REQ BY A. GARLINGTON	20 APR 2001
C	ADDED NOTE "4". REQ BY S. RIGGS	27 JUN 2003
D	ADDED FOOTPRINT INFORMATION. UPDATED MARKING. REQ. BY D. JOERSZ	07 APR 2005
E	CHANGED DEVICE MARKING FROM AWW TO AYW. REQ. BY J. MANES.	14 SEP 2005
F	UPDATED DRAWINGS TO LATEST JEDEC STANDARDS. ADDED NOTE 5. REQ. BY T. GURNETT.	07 JUN 2006
G	ADDED MARKING DIAGRAM FOR IC OPTION. REQ. BY J. MILLER.	21 FEB 2007
H	CORRECTED MARKING DIAGRAM ERROR BY REVERSING ANALOG AND DISCRETE LABELS. REQ. BY GK SUA.	18 MAY 2007

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